

Type number	Package	Package description	Total product weight
PMDXB600UNEL	SOT1216	DFN1010B-6	1.21701 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
934070432147	2	1	260	30 s	1	235	20 s	3	Dongguan, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product	
Adhesive	Additive	Non hazardous	Proprietary	0.00022	1.00000	0.01808	
	Filler	Silver (Ag)	7440-22-4	0.01848	84.00000	1.51848	
	Polymer	Bismaleimidodiphenylmethane resin			0.00220	10.00000	0.18077
		Isobornyl Methacrylate	7534-94-3	0.00110	5.00000	0.09039	
		subTotal		0.02200	100.00000	1.80772	
Die	Doped silicon	Silicon (Si)	7440-21-3	0.06000	100.00000	4.93012	
		subTotal		0.06000	100.00000	4.93012	
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.44769	91.18000	36.78637	
		Magnesium (Mg)	7439-95-4	0.00083	0.17000	0.06859	
		Nickel (Ni)	7440-02-0	0.01394	2.84000	1.14579	
		Silicon (Si)	7440-21-3	0.00304	0.62000	0.25014	
	Pure metal layer	Gold (Au)	7440-57-5	0.00034	0.07000	0.02824	
		Nickel (Ni)	7440-02-0	0.02303	4.69000	1.89217	
		Palladium (Pd)	7440-05-3	0.00211	0.43000	0.17348	
		subTotal		0.49100	100.00000	40.34478	
Mould Compound	Filler	Silica -amorphous-	7631-86-9	0.12120	20.00000	9.95883	
		Silica fused	60676-86-0	0.39087	64.50000	32.11724	
	Flame retardant	Metal hydroxide	Proprietary	0.01818	3.00000	1.49383	
	Impurity	Silicon Dioxide (SiO2)	14808-60-7	0.00303	0.50000	0.24897	
	Pigment	Carbon black	1333-86-4	0.00182	0.30000	0.14938	
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.01333	2.20000	1.09547	
		Phenolic resin	Proprietary	0.01515	2.50000	1.24485	
	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.04242	7.00000	3.48559		
		subTotal		0.60600	100.00000	49.79416	
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00000	0.01000	0.00020	
		Bismuth (Bi)	7440-69-9	0.00000	0.02000	0.00039	
		Iron (Fe)	7439-89-6	0.00000	0.01000	0.00020	
		Lead (Pb)	7439-92-1	0.00000	0.01000	0.00020	
	Tin solder	Tin (Sn)	7440-31-5	0.02399	99.95000	1.97106	
		subTotal		0.02400	100.00000	1.97205	
Wire	Impurity	Non hazardous	Proprietary	0.00000	0.01000	0.00012	
	Pure metal	Gold (Au)	7440-57-5	0.01400	99.99000	1.15071	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
		subTotal		0.01401	100.00000	1.15083

#### Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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